



SLOVENSKI STANDARD SIST EN 60603-7:2002

01-september-2002

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kSIST FprEN 60603-7:2008

Connectors for frequencies below 3 MHz for use with printed boards - Part 7: Detail specification for connectors, 8-way, including fixed and free connectors with common mating features, with assessed quality (IEC 60603-7:1996)

Connectors for frequencies below 3 MHz for use with printed boards -- Part 7: Detail specification for connectors, 8-way, including fixed and free connectors with common mating features, with assessed quality

ITeH STANDARD PREVIEW
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Steckverbinder für Frequenzen unter 3 MHz für gedruckte Schaltungen -- Teil 7: Bauartspezifikation für Steckverbinder mit bewerteter Qualität, 8-polig, einschließlich fester und freier Steckverbinder mit gemeinsamen Steckmerkmalen

SIST EN 60603-7:2002
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Connecteurs pour fréquences inférieures à 3 MHz pour utilisation avec cartes imprimées -- Partie 7: Spécification particulière pour connecteurs à 8 voies, comprenant des embases et des fiches ayant des caractéristiques d'accouplement communes, avec assurance de la qualité

Ta slovenski standard je istoveten z: EN 60603-7:1997

ICS:

31.220.10 Xcã áñ Ácã } ã^É [} ^\ d |ã Plug-and-socket devices.
Connectors

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60603-7

January 1997

ICS 31.220.10

Supersedes EN 60603-7:1993

Descriptors: Printed board connector, 8-way, ISDN

English version

**Connectors for frequencies below 3 MHz for use with printed boards
Part 7: Detail specification for connectors, 8-way, including fixed and
free connectors with common mating features, with assessed quality
(IEC 603-7:1996)**

Connecteurs pour fréquences inférieures
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Steckverbinder mit bewerteter Qualität,
8-polig, einschließlich fester und freier

Steckverbinder mit gemeinsamen
Steckmerkmalen

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This European Standard was approved by CENELEC on 1996-12-09. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 48B/489/FDIS, future edition 2 of IEC 603-7, prepared by SC 48B, Connectors, of IEC TC 48, Electromechanical components and mechanical structures for electronic equipment, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60603-7 on 1996-12-09.

This European Standard supersedes EN 60603-7:1993.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 1997-09-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 1997-09-01

Annexes designated "normative" are part of the body of the standard. In this standard, annexes A, B, C, D and ZA are normative. Annex ZA has been added by CENELEC.

Information from the foreword of the International Standard considered necessary:

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this International Standard may involve the use of a patent concerning connectors, 8-way, for interconnect systems given in clauses 3 and 4.

SIST EN 60603-7:2002

The IEC takes no position concerning the evidence, validity and scope of this patent right.

9c575d3b4c70/sist-en-60603-7-2002

The holder of this patent right has assured the IEC that he is willing to negotiate licences under reasonable and non-discriminatory terms and conditions with applicants throughout the world. In this respect, the statement of the holder of this patent right is registered with the IEC. Information may be obtained from:

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United States of America

Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights other than those identified above. IEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 603-7:1996 was approved by CENELEC as a European Standard without any modification.



Annex ZA (normative)

Normative references to international publications
with their corresponding European publications

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE: When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 50(581)	1978	International Electrotechnical Vocabulary (IEV) Chapter 581: Electromechanical components for electronic equipment	-	-
IEC 68-1	1988	Environmental testing Part 1: General and guidance	EN 60068-1 ¹⁾	1994
IEC 326-3	1991	Printed boards Part 3: Design and use of printed boards	-	-
IEC 352-2	1990	Solderless connections Part 2: Solderless crimped connections General requirements, test methods and practical guidance	EN 60352-2	1994
IEC 352-3	1993	Part 3: Solderless accessible insulation displacement connections - General requirements, test methods and practical guidance	EN 60352-3	1994
IEC 352-4	1994	Part 4: Solderless non-accessible insulation displacement connections - General requirements, test methods and practical guidance	EN 60352-4	1994
IEC 410	1973	Sampling plans and procedures for inspection by attributes	-	-
IEC 512-2	1985	Electromechanical components for electronic equipment - Basic testing procedures and measuring methods Part 2: General examination, electrical continuity and contact resistance tests, insulation tests and voltage stress tests	-	-

1) EN 60068-1 includes the corrigendum October 1988 and A1:1992 to IEC 68-1.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 512-3	1976	Part 3: Current-carrying capacity tests	-	-
IEC 512-4	1976	Part 4: Dynamic stress tests	-	-
IEC 512-5	1992	Part 5: Impact tests (free components), static load tests (fixed components), endurance tests and overload tests	-	-
IEC 512-6	1984	Part 6: Climatic tests and soldering tests	-	-
IEC 512-7	1988	Part 7: Mechanical operating tests and sealing tests	-	-
IEC 512-8	1993	Part 8: Connector tests (mechanical) and mechanical tests on contacts and terminations	-	-
IEC 603-1	1991	Connectors for frequencies below 3 MHz for use with printed boards Part 1: Generic specification - General requirements and guide for the preparation of detail specifications, with assessed quality	-	-
A1	1992		-	-
IEC 664-1 (mod)	1992	Insulation coordination for equipment within low-voltage systems Part 1: Principles, requirements and tests	HD 625.1 S1 + corr. November 1996	1996
IEC 807-1	1991	Rectangular connectors for frequencies below 3 MHz Part 1: Generic specification General requirements and guide for the preparation of detail specifications for connectors with assessed quality	-	-
IEC QC 001001	1986	Basic rules of the IEC Quality Assessment System for Electronic Components (IECQ)	-	-
A2	1994		-	-
A3	1995		-	-
IEC QC 001002	1986	Rules of procedure of the IEC Quality Assessment System for Electronic Components (IECQ)	-	-
A2	1994		-	-
ISO 468	1982	Surface roughness - Parameters, their values and general rules for specifying requirements	-	-
ITU-T K20	1984	Resistibility of telecommunication switching equipment to overvoltages and overcurrents	-	-

**NORME
INTERNATIONALE
INTERNATIONAL
STANDARD**

**CEI
IEC**

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QC 010000XX0003

Deuxième édition
Second edition
1996-11

**Connecteurs pour fréquences inférieures à 3 MHz
pour utilisation avec cartes imprimées –**

Partie 7:

**Spécification particulière pour connecteurs
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**Connectors for frequencies below 3 MHz
for use with printed boards –**

Part 7:

**Detail specification for connectors, 8-way,
including fixed and free connectors with common
mating features, with assessed quality**

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Международная Электротехническая Комиссия

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For price, see current catalogue

CONTENTS

	Page
FOREWORD	5
Clause	
1 Scope.....	9
2 IEC type designation.....	13
3 Common features and isometric view	14
3.1 Isometric view.....	14
3.2 Mating information	15
3.3 Survey of types.....	25
4 Dimensions	25
4.1 General	25
4.2 Type A – Fixed connectors (panel-mounted)	26
4.3 Type B – Fixed connectors (board-mounted)	32
4.4 Type C – Free connectors.....	47
4.5 Type D – Free coupler connectors (under consideration)	48
4.6 Mounting information for type A fixed connectors (panel-mounted)	49
4.7 Mounting information for type B fixed connectors (board-mounted)	52
5 Gauges	53
5.1 Fixed connectors	53
5.2 Free connectors.....	56
5.3 Test panels (for voltage proof test).....	60
6 Characteristics	61
6.1 Climatic category	61
6.2 Electrical	61
6.3 Mechanical	65
7 Test schedule	65
8 Quality assessment procedures	83
8.1 Qualification approval testing	83
8.2 Quality conformance inspection.....	85
Annexes	
A Gauging requirements	89
B Locking device mechanical operation – Test procedure and requirements.....	91
C Gauging continuity procedure.....	93
D Flowing mixed gas corrosion test	99

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**CONNECTORS FOR FREQUENCIES BELOW 3 MHz
FOR USE WITH PRINTED BOARDS –**

**Part 7: Detail specification for connectors, 8-way,
including fixed and free connectors with common mating features,
with assessed quality**

FOREWORD

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of the IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested National Committees.
- 3) The documents produced have the form of recommendations for international use and are published in the form of standards, technical reports or guides and they are accepted by the National Committees in that sense.
- 4) In order to promote international unification, IEC National Committees undertake to apply IEC International Standards transparently to the maximum extent possible in their national and regional standards. Any divergence between the IEC Standard and the corresponding national or regional standard shall be clearly indicated in the latter.
- 5) The IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with one of its standards.
- 6) Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. The IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 603-7 has been prepared by subcommittee 48B: Connectors, of IEC technical committee 48: Electromechanical components and mechanical structures for electronic equipment.

This second edition cancels and replaces the first edition published in 1990 and constitutes a technical revision.

The text of this standard is based on the following documents:

FDIS	Report on voting
48B/489/FDIS	48B/546/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this International Standard may involve the use of a patent concerning connectors, 8-way, for interconnect systems given in clauses 3 and 4.

The IEC takes no position concerning the evidence, validity and scope of this patent right.

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Annexes A, B, C and D form an integral part of this document.

The QC number that appears on the front cover of this publication is the specification number in the IEC Quality Assessment Systems for Electronic Components (IECQ).

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CONNECTORS FOR FREQUENCIES BELOW 3 MHz FOR USE WITH PRINTED BOARDS –

Part 7: Detail specification for connectors, 8-way, including fixed and free connectors with common mating features, with assessed quality

1 Scope

This part of IEC 603 covers an 8-way connector system of 4, 6 or 8 contacts consisting of a range of free and fixed connectors. The connectors cover a variety of different mounting configurations and termination types with a common mating configuration.

Fixed connectors are provided with terminations suitable for solder, insulation displacement, screw terminal, crimp, insulation piercing termination, printed-board mounting and flying leads.

Free connectors are provided for crimp, insulation piercing and insulation displacement terminations to cable assemblies with tinsel, stranded or solid wire conductors. At the present time, free connectors may only be available with a limited range of terminations and variants.

1.1 Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 603. At the time of publication, the editions indicated were valid. All normative documents are subject to revision, and parties to agreements based on this part of IEC 603 are encouraged to investigate the possibility of applying the most recent editions of the normative documents indicated below. Members of IEC and ISO maintain registers of currently valid International Standards.

IEC 50(581): 1978, *International Electrotechnical Vocabulary (IEV) – Chapter 581: Electro-mechanical components for electronic equipment*

IEC 68-1: 1988, *Environmental testing – Part 1: General and guidance*

IEC 326-3: 1991, *Printed boards – Part 3: Design and use of printed boards*

IEC 352-2: 1990, *Solderless connections – Part 2: Solderless crimped connections – General requirements, test methods and practical guidance*

IEC 352-3: 1993, *Solderless connections – Part 3: Solderless accessible insulation displacement connections – General requirements, test methods and practical guidance*

IEC 352-4: 1994, *Solderless connections – Part 4: Solderless non-accessible insulation displacement connections – General requirements, test methods and practical guidance*

IEC 410: 1973, *Sampling plans and procedures for inspection by attributes*

IEC 512-2: 1985, *Electromechanical components for electronic equipment, basic testing procedures and measuring methods – Part 2: General examination, electrical continuity and contact resistance tests, insulation tests and voltage stress tests*

IEC 512-3: 1976, *Electromechanical components for electronic equipment; basic testing procedures and measuring methods – Part 3: Current-carrying capacity tests*

IEC 512-4: 1976, *Electromechanical components for electronic equipment; basic testing procedures and measuring methods – Part 4: Dynamic stress tests*

IEC 512-5: 1992, *Electromechanical components for electronic equipment; basic testing procedures and measuring methods – Part 5: Impact tests (free components), static load tests (fixed components), endurance tests and overload tests*

IEC 512-6: 1984, *Electromechanical components for electronic equipment; basic testing procedures and measuring methods – Part 6: Climatic tests and soldering tests*

IEC 512-7: 1988, *Electromechanical components for electronic equipment; basic testing procedures and measuring methods – Part 7: Mechanical operating tests and sealing tests*

IEC 512-8: 1993, *Electromechanical components for electronic equipment; basic testing procedures and measuring methods – Part 8: Connector tests (mechanical) and mechanical tests on contacts and terminations*

IEC 603-1: 1991, *Connectors for frequencies below 3 MHz for use with printed boards – Part 1: Generic specification – General requirements and guide for the preparation of detail specifications, with assessed quality*
Amendment 1 (1992)

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IEC 664-1: 1992, *Insulation coordination for equipment within low-voltage systems – Part 1: Principles, requirements and tests*

IEC 807-1: 1991, *Rectangular connectors for frequencies below 3 MHz – Part 1: Generic specification – General requirements and guide for the preparation of detail specifications for connectors with assessed quality*

IEC QC 001001: 1986, *Basic rules of the IEC quality assessment system for electronic components (IECQ)*
Amendment 2 (1994)
Amendment 3 (1995)

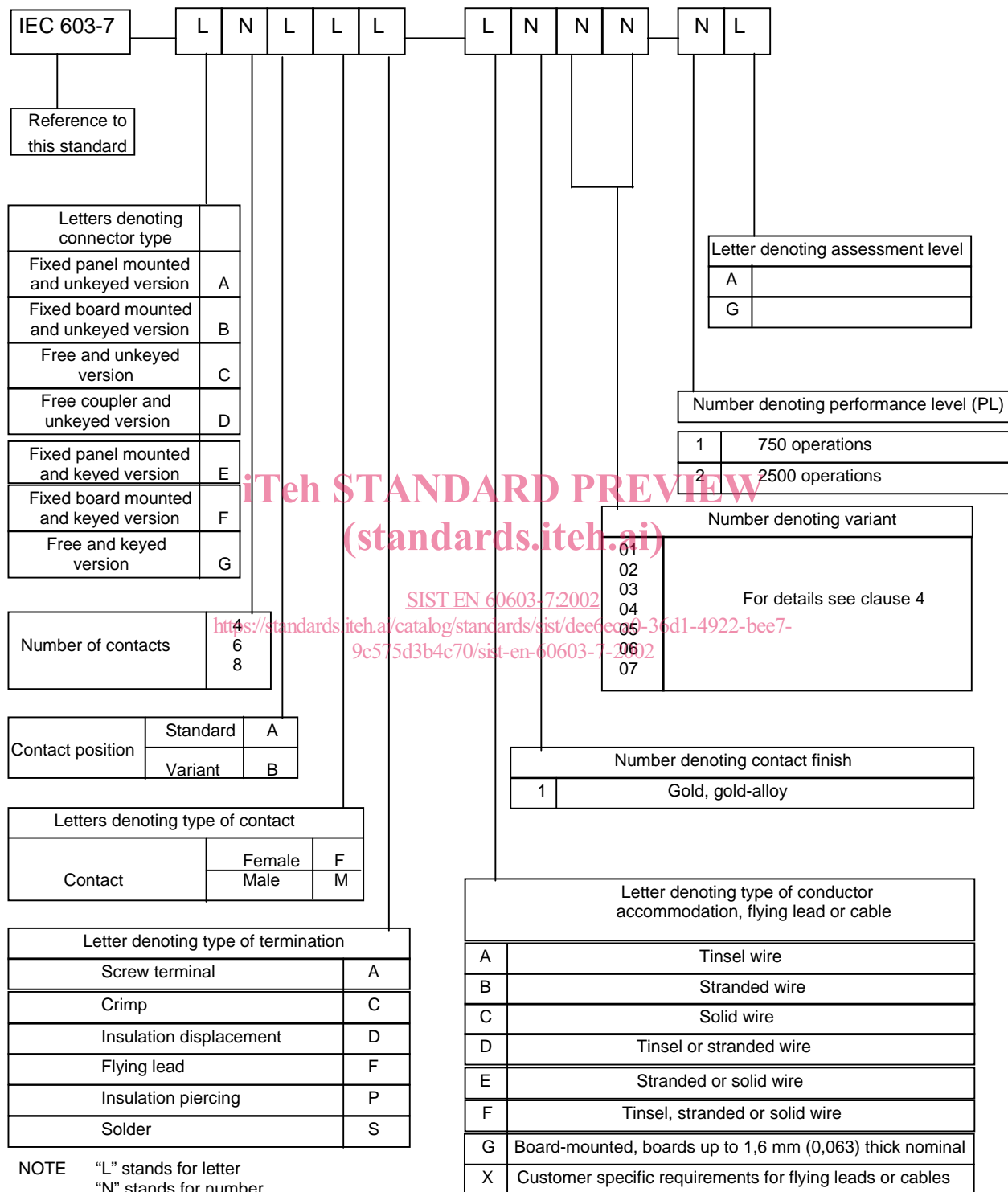
IEC QC 001002: 1986, *Rules of procedure of the IEC quality assessment system for electronic components (IECQ)*
Amendment 2 (1994)

ISO 468: 1982, *Surface roughness – Parameters, their values and general rules for specifying requirements*

ITU-T K20: 1984, *Resistibility of telecommunication switching equipment to overvoltages and overcurrents*

2 IEC type designation

Connectors, connector bodies and connectors with pre-inserted contacts according to this standard shall be designated by the following system:



Example:

IEC 603-7 B8AFS-G101- 2G: Fixed connector, board mounted, unkeyed having 8 female contacts in standard contact positions, gold plated to be soldered into a printed board having a thickness of 1,6 mm nominal variant 01, meeting performance level 2, assessment level G.

3.2 Informations concernant la face d'accouplement

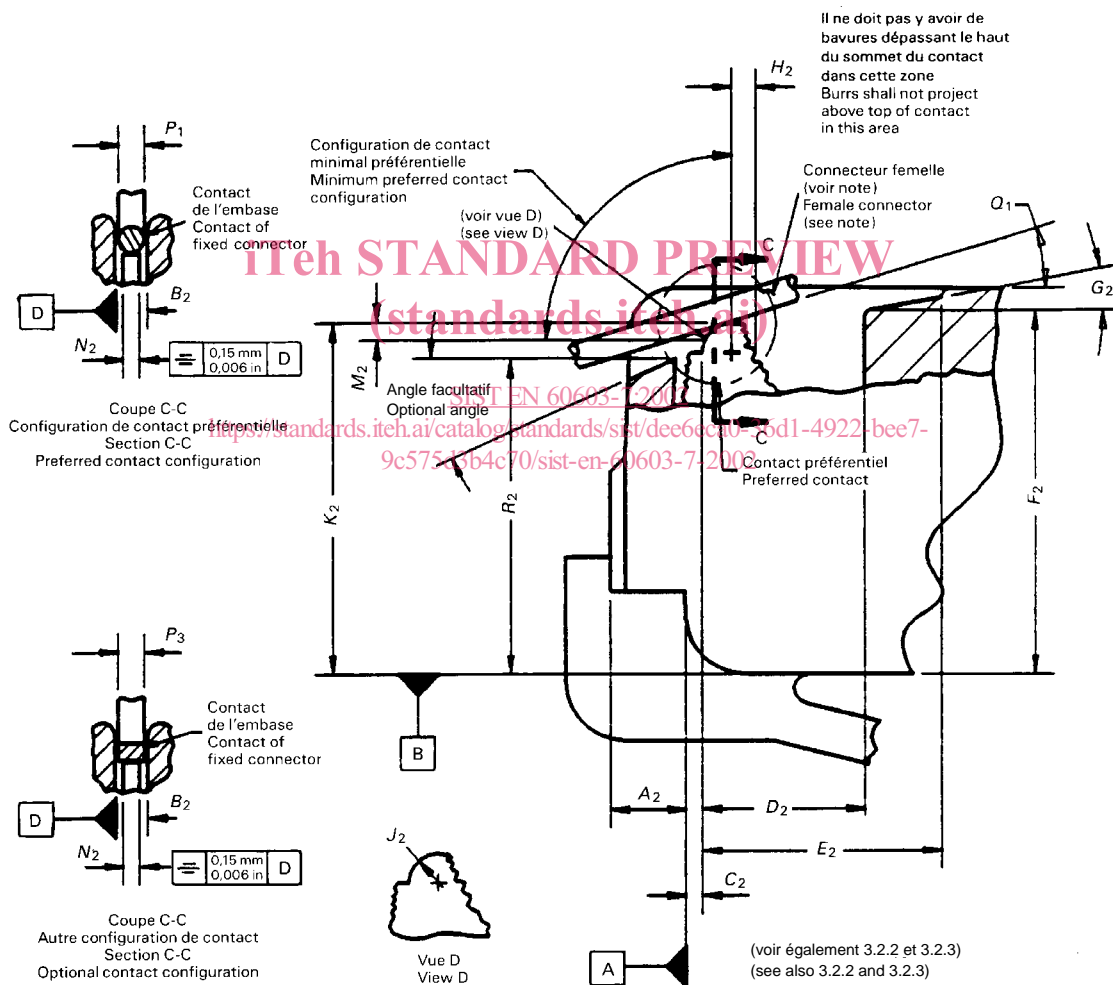
Pour les besoins de cette spécification, les informations concernant les dimensions sont détaillées en plus de celles qui sont spécifiées dans la CEI 603-1 (et dans la CEI 807-1). Il est donc nécessaire de lire ensemble 3.2.1 à 3.2.3 inclus.

3.2.1 Contacts

3.2 Mating information

For the purpose of this specification, dimensional information in excess of that specified in IEC 603-1 (and IEC 807-1) is detailed. It is, therefore, necessary to read 3.2.1 to 3.2.3 inclusive in conjunction with each other.

3.2.1 Contacts



NOTE – Les informations montrées concernant la face d'accouplement ne peuvent être respectées qu'avec une fiche équipée de câble.

NOTE – The mating information shown can only be achieved with a free connector with cable attached.

3.2.2 *Embase*

3.2.2 *Fixed connector*

